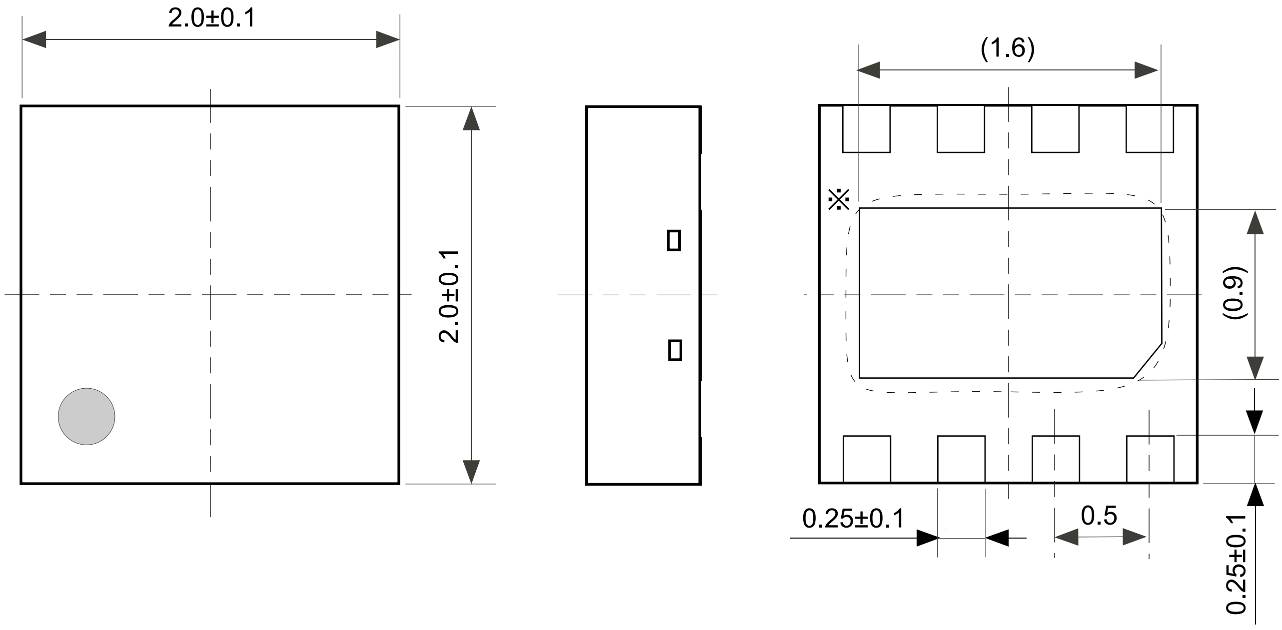

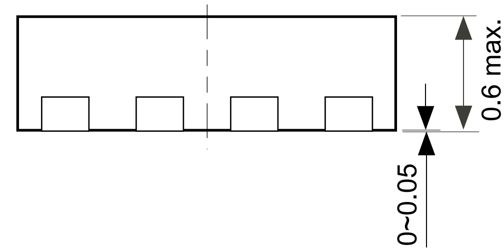

※ The heat sink of back side has different electric potential depending on the product.
Confirm specifications of each product.
Do not use it as the function of electrode.

No. IB008-A-P-SD-1.0

TITLE	DFN-8-E-PKG Dimensions
No.	IB008-A-P-SD-1.0
ANGLE	
UNIT	mm

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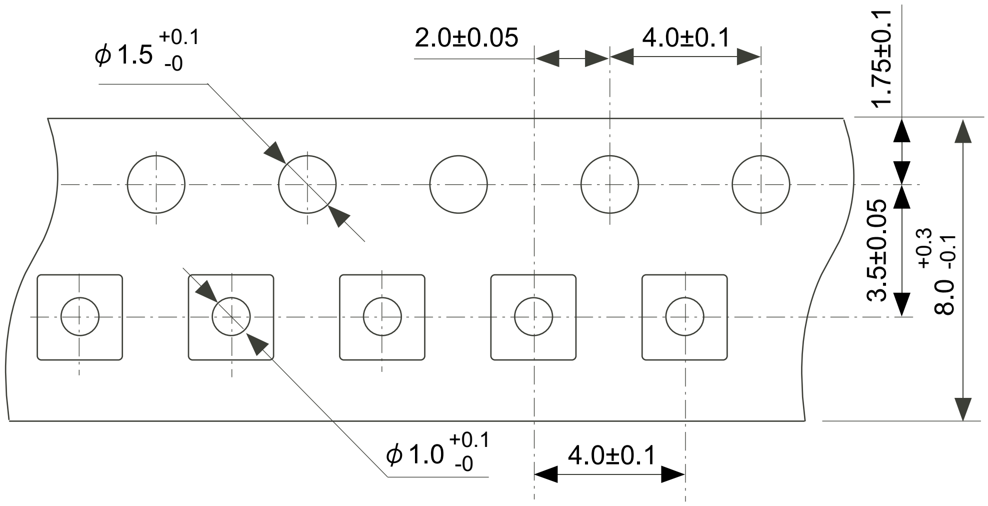
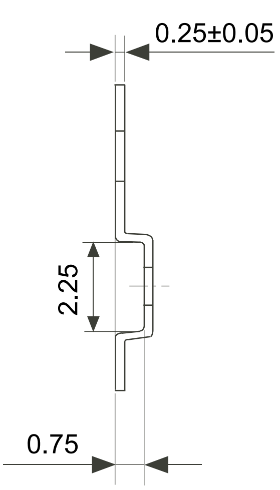
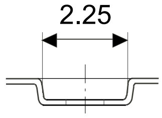
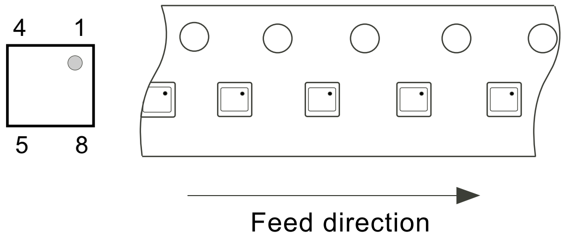




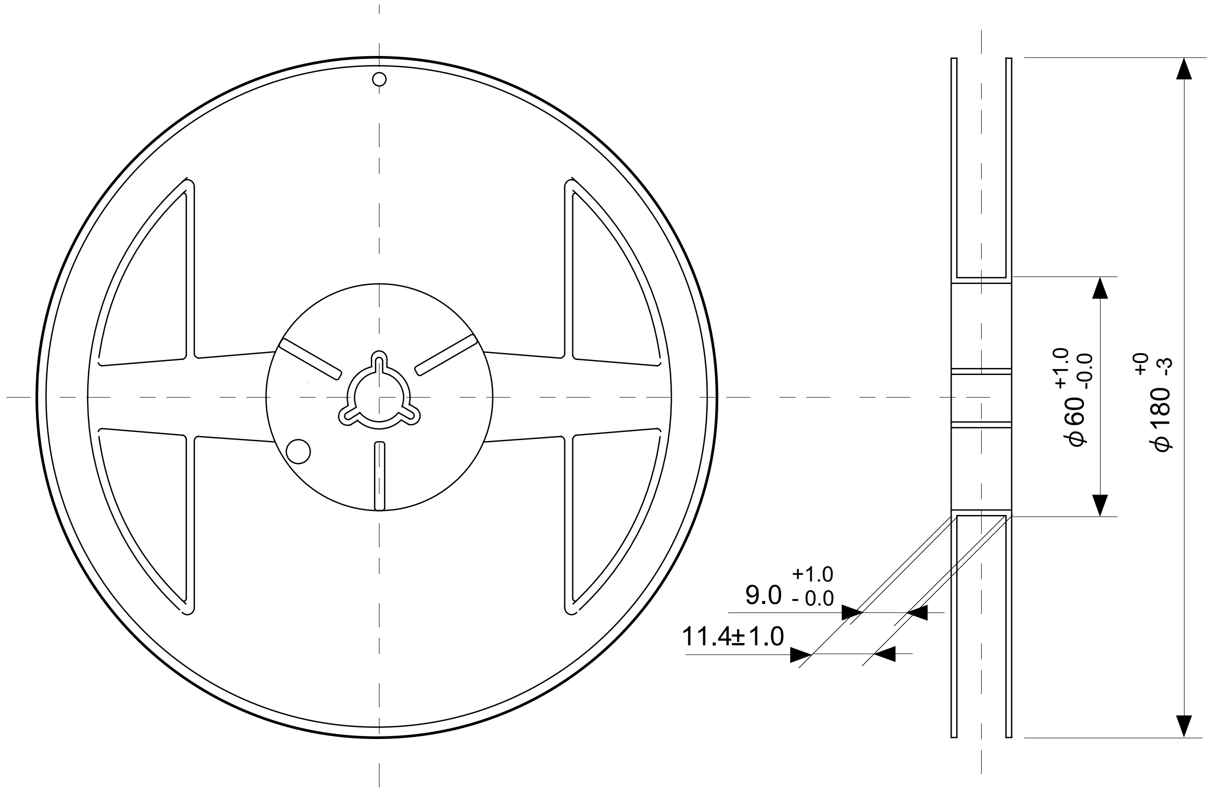




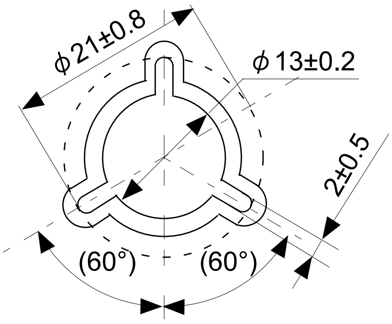
No. IB008-A-C-SD-1.0

TITLE	DFN-8-E-Carrier Tape
No.	IB008-A-C-SD-1.0
ANGLE	
UNIT	mm

ABLIC Inc.



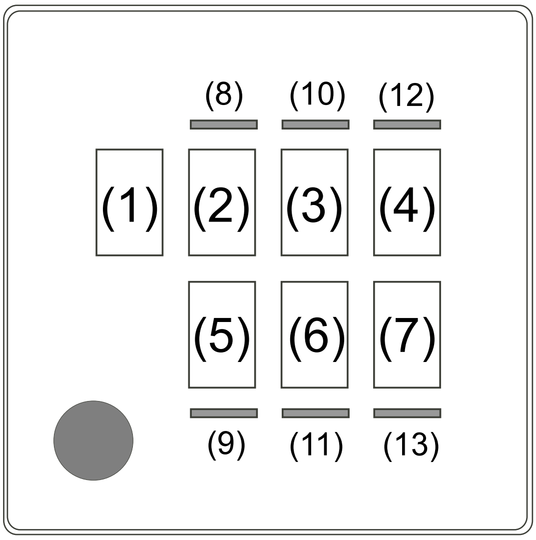
Enlarged drawing in the central part



No. IB008-A-R-SD-1.0

TITLE	DFN-8-E-Reel		
No.	IB008-A-R-SD-1.0		
ANGLE		QTY.	4,000
UNIT	mm		

ABLIC Inc.



(1) to (4) : Product code

(5) to (7) : Lot No.

(8) , (9) : Year of assembly (bar)

(10) to (13) : Month of assembly (bar)

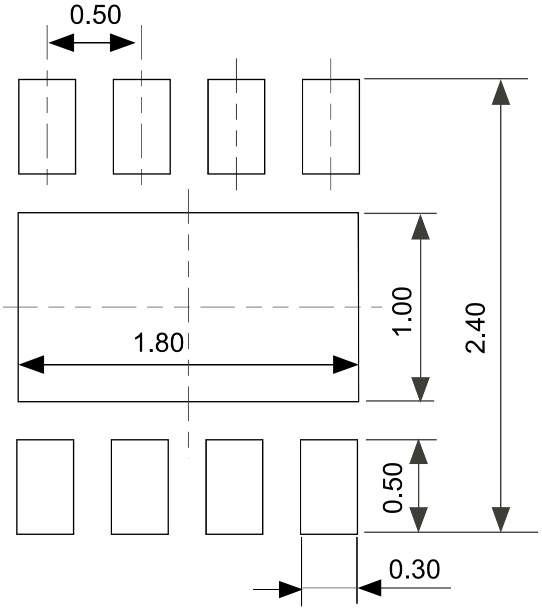
● : 1Pin mark

No. IB008-A-M-SD-1.0

TITLE	DFN-8-E-Markings		
No.	IB008-A-M-SD-1.0		
ANGLE			
UNIT		TYPE	LASER

ABLIC Inc.

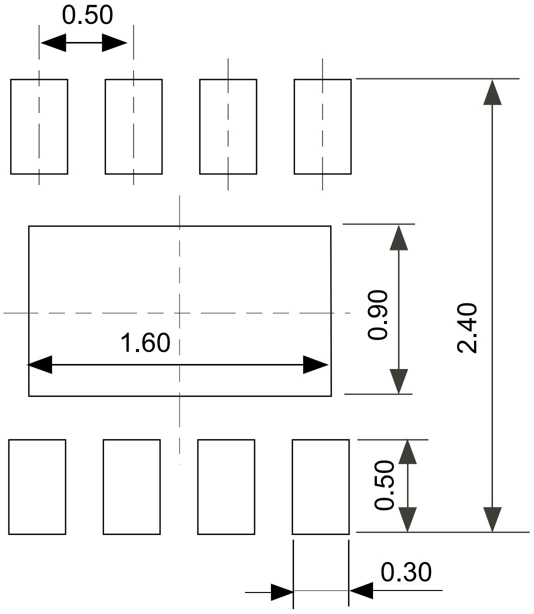
Land Pattern



Cauion It is recommended to solder the heat sink to a board
in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板（ヒートシンク）を基板に
半田付けする事を推奨いたします。

Metal Mask Pattern



Caution
① Mask aperture ratio of the lead mounting part is 100%.
② Mask aperture ratio of the heat sink mounting part is 80%.
③ Mask thickness: t0.12 mm

注意
①リード実装部のマスク開口率は100%です。
②放熱板実装のマスク開口率は80%です。
③マスク厚み：t0.12 mm

TITLE	DFN-8-E -Land Recommendation
No.	IB008-A-L-SD-1.0
ANGLE	
UNIT	mm

ABLIC Inc.